CloudDC A+ Server AS -1115CS-TNR-01-G2

1U CloudDC with 10 hot-swap 2.5" NVMe/SAS/SATA bays and 2 PCIe 5.0 x16 slots + 2 AIOM slots

More details here

Key Applications

Compute/Metadata Node for AI Storage Cluster

Gold Configuration Details

- CPU: 1x AMD EPYC™ 9555P (64C/3.2GHz)
- Memory: 384GB DDR5-6400
- Storage: 1x 960GB U.2 NVMe SSD
- NIC: 2x NVIDIA® ConnectX®-7 VPI dual 200G QSFP56
- NIC: 1x quad 1GbE RJ45
- Power: 2x 860W Platinum Level



Base System Specs

Form Factor	1U Rackmount Enclosure: 437 x 43 x 597mm (17.2" x 1.7" x 23.5") Package: 605 x 197 x 822mm (23.8" x 7.8" x 32.4")
Processor	Single processor(s) AMD EPYC™ 9004/9005 Series Processors (* AMD EPYC™ 9005 Series drop-in support requires board revision 2.x) Up to 160C/320T
GPU	Max GPU Count: Up to 2 single-width GPUs Supported GPU: NVIDIA PCIe: A2, L4 CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect GPU-GPU Interconnect: PCIe
System Memory	Slot Count: 12 DIMM slots Max Memory (1DPC): Up to 3TB 4800MT/s ECC DDR5 RDIMM (AMD EPYC™ 9004 Series Processor, MB R1.x/R2.0/R2.01) Max Memory (1DPC): Up to 3TB 6000MT/s ECC DDR5 RDIMM (AMD EPYC™ 9005 Series Processor, MB R2.0) Max Memory (1DPC): Up to 3TB 6400MT/s ECC DDR5 RDIMM (AMD EPYC™ 9005 Series Processor, MB R2.01)
Drive Bays Configuration	(*NVMe/SAS support may require additional storage controller and/or cables, please see the optional parts list for details) M.2: 2 M.2 PCIe 3.0 x2 NVMe slots (M-key 2280/22110)
On-Board Devices	Chipset: AMD System on Chip Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 ports (rear) 2 USB 2.0 ports (front) Video: 1 VGA port Serial: 1 COM port (rear) TPM: 1 TPM header

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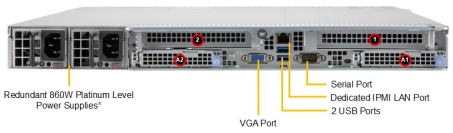
(Front View – System)



Drive Bay	Description
0 – 10	10 Hot-swap 2.5" NVMe*/SAS*/SATA Drive Bays

*NVMe and SAS support requires additional parts from the optional parts list.

(Rear View – System)



	Slot Description
1	PCIe 5.0 x16 FHHL
2	PCIe 5.0 x16 FHHL
A1	PCIe 5.0 x16 AIOM (OCP 3.0)
A2	PCIe 5.0 x16 AIOM (OCP 3.0)

*Full redundancy based on configuration and application load.

System Cooling	Fans: Up to 6x 4cm heavy duty fans with optimal fan speed control Air Shroud: 1 Air Shroud
Power Supply	2x 860W Redundant (1 + 1) Platinum Level (94%) power supplies
System BIOS	BIOS Type: AMI 32MB SPI Flash ROM BIOS Features: ACPI 6.4 Plug and Play (PnP) SMBIOS 3.5 or later UEFI 2.8 USB Keyboard support
Management	SuperCloud Composer® (SCC); Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); OOB Management Package (SFT-OOB-LIC); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	Fan: Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors Voltage: System temperature, Memory temperature, CPU temperature, 3.3V standby, +5V standby, +5V, +3.3V, +12V, CPU thermal trip support
Dimensions and Weight	Weight: Gross Weight: 46 lbs (20.9 kg) Net Weight: 25 lbs (11.3 kg) Available Color: Black front & sliver body
Operating Environment	Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	**A+ Motherboard® H13SSW**
Chassis	**CSE-LB16TS-R860AWP-A**

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